

#### SCR Diode Array for ESD and Transient Overvoltage Protection

### **SP724**

#### **Absolute Maximum Ratings** Continuous Supply Voltage, (V+) - (V-)....+20V Forward Peak Current, $I_{\mbox{\footnotesize{IN}}}$ to $V_{\mbox{\footnotesize{CC}}}$ , GND (Refer to Figure 6).....±2.2A, 100µs ESD Ratings and Capability - See Figure 1, Table 1

#### **Thermal Information**

Thermal Resistance (Typical, Note 3)	θ <sub>JA</sub> (°C/W)
SOT Package	220
Maximum Storage Temperature Range	65°C to 150°C
Maximum Junction Temperature	150°C
Maximum Lead Temperature (Soldering 10s)	300°C
(SOT - Lead Tips Only)	

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

3.  $\theta_{JA}$  is measured with the component mounted on an evaluation PC board in free air.

**Electrical Specifications**  $T_A = -40^{\circ}C$  to  $105^{\circ}C$ ,  $V_{IN} = 0.5V_{CC}$ , Unless Otherwise Specified

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Operating Voltage Range, V <sub>SUPPLY</sub> = [(V+) - (V-)] (Notes 4, 5)	V <sub>SUPPLY</sub>		1	-	20	V
Forward Voltage Drop						
IN to V-	$V_{FWDL}$	I <sub>IN</sub> = 1A (Peak Pulse)	-	2	-	V
IN to V+	V <sub>FWDH</sub>		-	2	-	V
Input Leakage Current	I <sub>IN</sub>		-10	1	10	nA
Quiescent Supply Current	IQUIESCENT	V+ = 20V, V- = GND	-	-	100	nA
Equivalent SCR ON Threshold		(Note 6)	-	1.1	-	V
Equivalent SCR ON Resistance		V <sub>FWD</sub> /I <sub>FWD</sub> (Note 6)	-	1.0	-	Ω
Input Capacitance	C <sub>IN</sub>		-	3	-	pF

#### NOTES:

- 4. In automotive and other battery charging systems, the SP724 power supply lines should be externally protected for load dump and reverse battery. When the V+ and V- Pins are connected to the same supply voltage source as the device or control line under protection, a current limiting resistor should be connected in series between the external supply and the SP724 supply pins to limit reverse battery current to within the rated maximum limits.
- 5. Bypass capacitors of typically 0.01 μF or larger should be connected closely between the V+ and V- Pins for all applications.
- 6. Refer to the Figure 3 graph for definitions of equivalent "SCR ON Threshold" and "SCR ON Resistance". These characteristics are given here for information to determine peak current and dissipation under EOS conditions.

### ESD Rating

ESD rating is dependent on the defined test standard. The evaluation results for various test standards and methods based on Figure 1 are shown in Table 1.3

The SP724 has a Level 4 rating when tested to the IEC 61000-4-2 Human Body Model (HBM) standard and connected in a circuit in which the V+ and V- pins have a return path to ground. Level 4 specifies a required capability greater than 8kV for direct discharge and greater than 15kV for air discharge.

The "Modified" MIL-STD-3015.7 condition is defined as an "in-circuit" method of ESD testing, the V+ and V- pins have a return path to ground. The SP724 ESD capability is greater than 8kV with 100pF discharged through 1.5k $\Omega$ . By strict definition of the standard MIL-STD-3015.7 method using "pin-to-pin" device testing, the ESD voltage capability is greater than 2kV.

For the SP724 EIAJ IC121 Machine Model (MM) standard, the ESD capability is typically greater than 1.8kV with 200pF discharged through  $0k\Omega$ .

The Charged Device model is based upon the self-capacitance of the SOT-23 package through  $0k\Omega$ .

#### TABLE 1. ESD TEST CONDITIONS

STANDARD	TYPE/MODE	$R_D$	CD	±V <sub>D</sub>
IEC 61000-4-2	HBM, Air Discharge	330Ω	150pF	15kV
(Level 4)	HBM, Direct Discharge	330Ω	150pF	8kV
MIL-STD-3015.7	Modified HBM	1.5kΩ	100pF	8kV†
	Standard HBM	1.5kΩ	100pF	2kV
EIAJ IC121	Machine Model	0kΩ	200pF	400V
US ESD DS 5.3	Charged Device Model	0kΩ	NA	3kV

<sup>†</sup>Upper limit of laboratory test set.

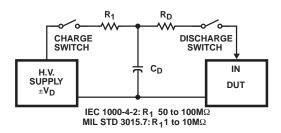
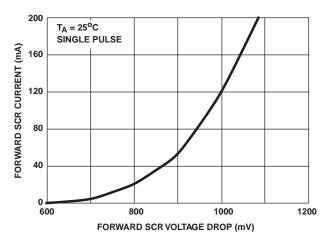


FIGURE 1. ELECTROSTATIC DISCHARGE TEST



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EQUIV. SAT. ON
THRESHOLD ~ 1.1V

FORWARD SCR VOLTAGE DROP (V)

T<sub>A</sub> = 25°C SINGLE PULSE

FIGURE 2. LOW CURRENT SCR FORWARD VOLTAGE DROP
CURVE

FIGURE 3. HIGH CURRENT SCR FORWARD VOLTAGE DROP
CURVE

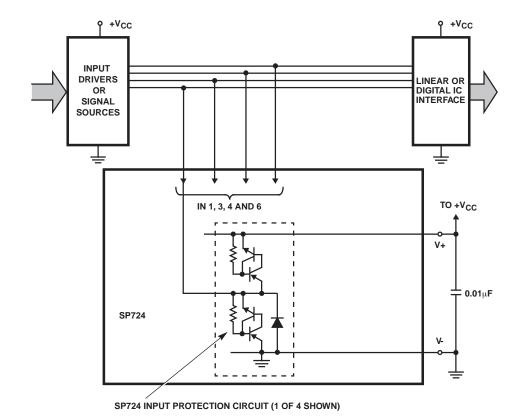


FIGURE 4. TYPICAL APPLICATION OF THE SP724 AS AN INPUT CLAMP FOR OVER-VOLTAGE, GREATER THAN 1VBE ABOVE V+ OR LESS THAN -1VBE BELOW V-



#### SCR Diode Array for ESD and Transient Overvoltage Protection

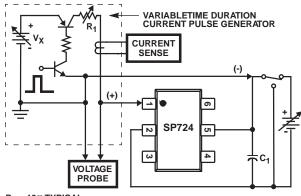
### **SP724**

#### Peak Transient Current Capability for Long Duration Surges

The peak transient current capability is inversely proportional to the width of the current pulse. Testing was done to fully evaluate the SP724's ability to withstand long duration current pulses using the circuit of Figure 5. Figure 6 shows the point of overstress as defined by increased leakage in excess of the data sheet published limits. The safe operating range of the transient peak current should be limited to no more than 75% of the measured overstress level for any given pulse width as shown in the curve of Figure 6.

The test circuit of Figure 5 is shown with a positive pulse input. For a negative pulse input, the (-) current pulse input goes to an SP724 'IN' input pin and the (+) current pulse input goes to the SP724 V- pin. The V+ to V- supply of the SP724 must be allowed to float. (i.e., It is not tied to the ground reference of the current pulse generator.)

Note that two input pins of the SP724 may be paralleled to improve current (and ESD) capability. The sustained peak current capability is increased to nearly twice that of a single pin.



R<sub>1</sub> ~ 10Ω TYPICAL V<sub>X</sub> ADJ. 10V/A TYPICAL C1 ~ 100uF

FIGURE 5. TYPICAL SP724 PEAK CURRENT TEST CIRCUIT WITH A VARIABLE PULSE WIDTH INPUT

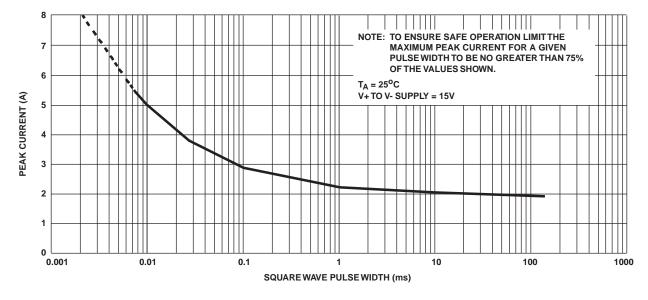


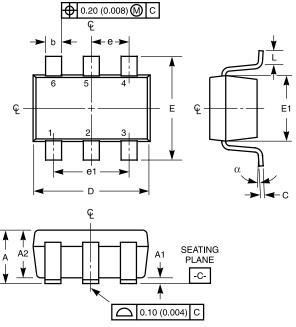
FIGURE 6. SP724 TYPICAL NONREPETITIVE PEAK CURRENT PULSE CAPABILITY



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### Small Outline Transistor Plastic Packages (SOT23-6)



#### NOTES:

- 1. Dimensioning and tolerances per ANSI 14.5M-1982.
- 2. Package conforms to EIAJ SC-74 (1992).
- Dimensions D and E1 are exclusive of mold flash, protrusions, or gate burrs.
- 4. Footlength L measured at reference to seating plane.
- 5. "L" is the length of flat foot surface for soldering to substrate.
- 6. "N" is the number of terminal positions.
- 7. Controlling dimension: MILLIMETER. Converted inch dimensions are not necessarily exact.

P6.064
6 LEAD SMALL OUTLINE TRANSISTOR PLASTIC PACKAGE

	INCHES		MILLIMETERS		
SYMBOL	MIN	MAX	MIN	MAX	NOTES
А	0.036	0.057	0.90	1.45	-
A1	0.000	0.0059	0.00	0.15	-
A2	0.036	0.051	0.90	1.30	-
b	0.0138	0.0196	0.35	0.50	-
С	0.0036	0.0078	0.09	0.20	-
D	0.111	0.118	2.80	3.00	3
Е	0.103	0.118	2.60	3.00	-
E1	0.060	0.068	1.50	1.75	3
е	0.0374 Ref		0.95	0.95 Ref	
e1	0.0748 Ref		1.90 Ref		-
L	0.004	0.023	0.10	0.60	4, 5
N	6		6		6
α	0°	10 <sup>0</sup>	0°	10 <sup>0</sup>	-

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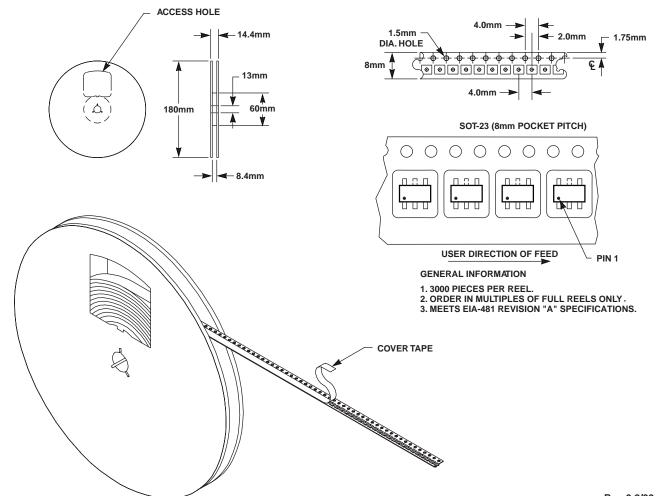


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### SOT23-6

**8mm TAPE AND REEL** 



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